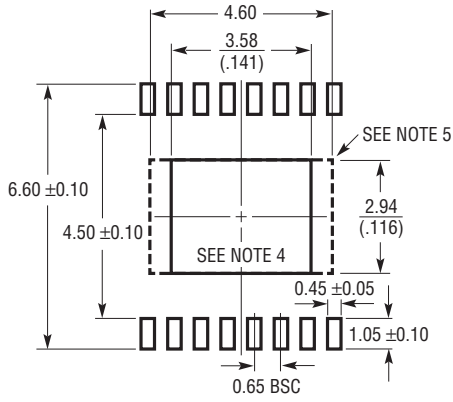
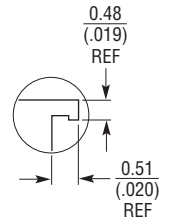
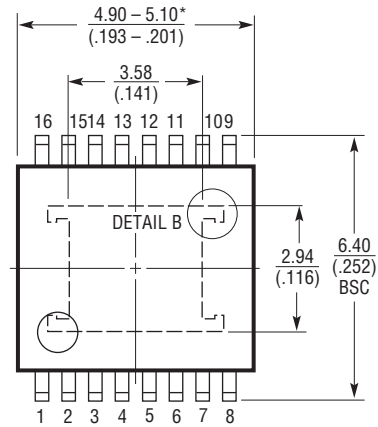


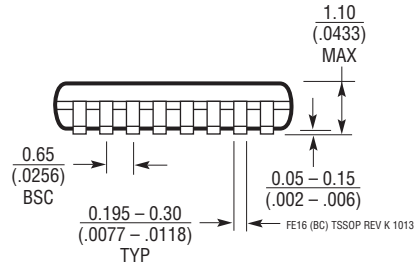
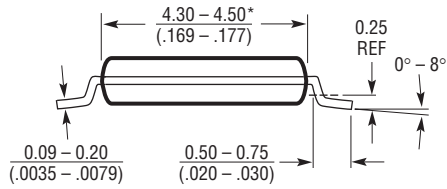
FE Package
16-Lead Plastic TSSOP (4.4mm)
 (Reference LTC DWG # 05-08-1663 Rev K)
Exposed Pad Variation BC



RECOMMENDED SOLDER PAD LAYOUT



DETAIL B IS THE PART OF THE LEAD FRAME FEATURE FOR REFERENCE ONLY
NO MEASUREMENT PURPOSE



NOTE:

1. CONTROLLING DIMENSION: MILLIMETERS
2. DIMENSIONS ARE IN $\frac{\text{MILLIMETERS}}{\text{(INCHES)}}$
3. DRAWING NOT TO SCALE
4. RECOMMENDED MINIMUM PCB METAL SIZE FOR EXPOSED PAD ATTACHMENT

5. BOTTOM EXPOSED PADDLE MAY HAVE METAL PROTRUSION IN THIS AREA. THIS REGION MUST BE FREE OF ANY EXPOSED TRACES OR VIAS ON PCB LAYOUT

*DIMENSIONS DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.150mm (.006") PER SIDE